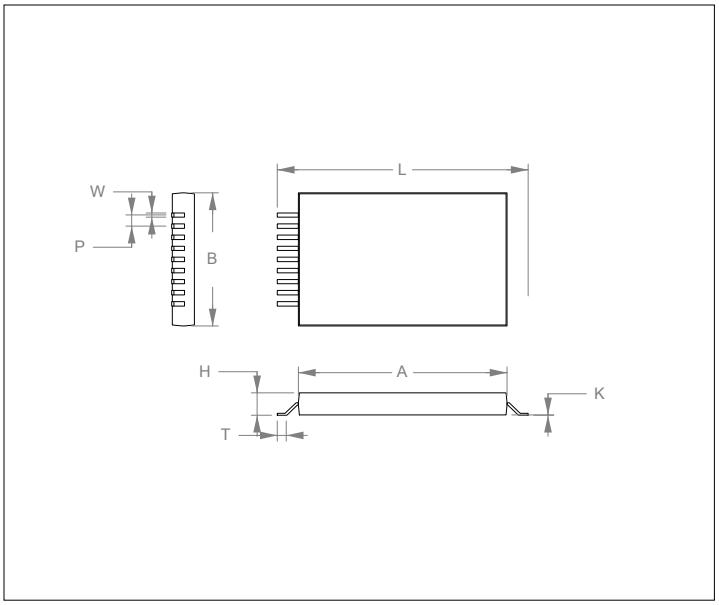
## Component (Fig. 1)

```
Small Outline IC (SOIC)
Pitch.....................1.00
Pin Package...............18
Pin Count.................9
Lmin......................22.60
Lmax......................22.60
Tmin......................0.80
Tmax......................0.80
Wmin......................0.40
Wmax......................0.40
Amin......................18.80
Amax......................18.80
Bmin......................12.00
Bmax......................12.00
Hmax......................2.04
Kmin......................0.05
```

Fig.1

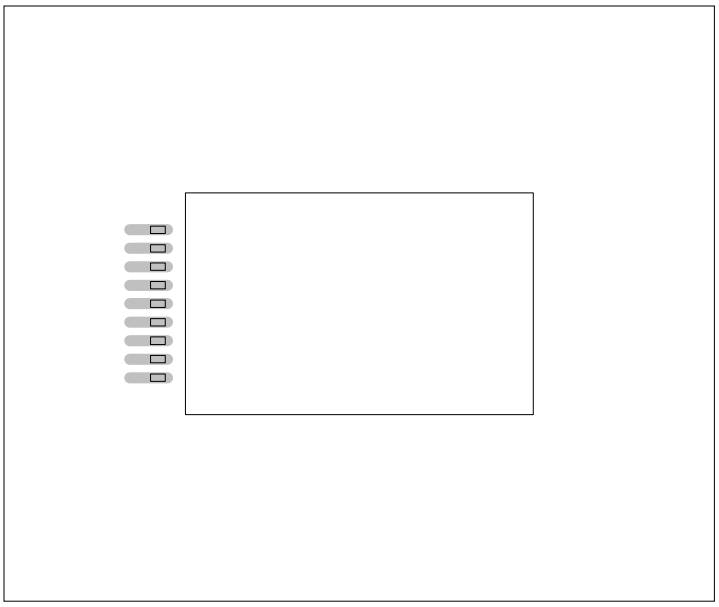



## Solder Joint Goals (Fig. 2)

```
Environment is USER

Toe(Outside)Goal..........1.35
Toe min...................1.35
Toe max...................1.43
Heel(Inside)Goal..........0.35
Heel Min..................0.35
Heel max..................0.43
Side Goal.................0.03
Side Min..................0.03
Side max..................0.10
```

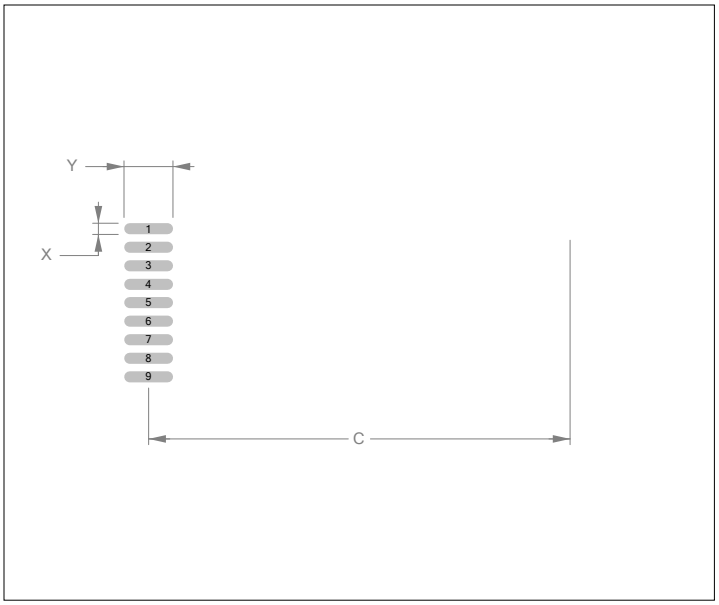
Fig.2



## Land Pattern (Fig. 3)

```
C.........................22.80
Y.........................2.65
X.........................0.60
Pin(s) default
b265_60
```

Fig.3



Silkscreen (Fig. 4)

```
R1.......................19.50
R2.......................12.00
```

Assembly (Fig. 5)

```
Anom.....................18.80
Bnom.....................12.00
```

Courtyard (Fig. 6)

```
V1.......................26.00
V2.......................12.50
```

Program Version: 2010.00.00

Advisories

```
None
```

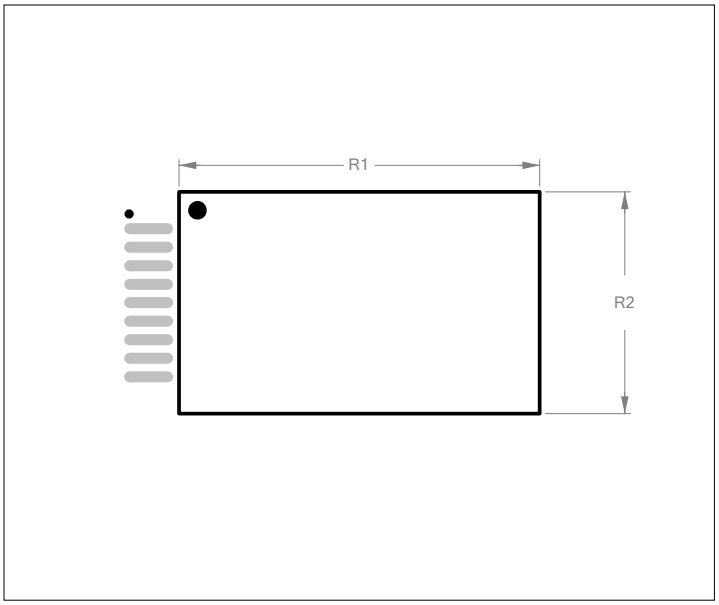



Fig.4

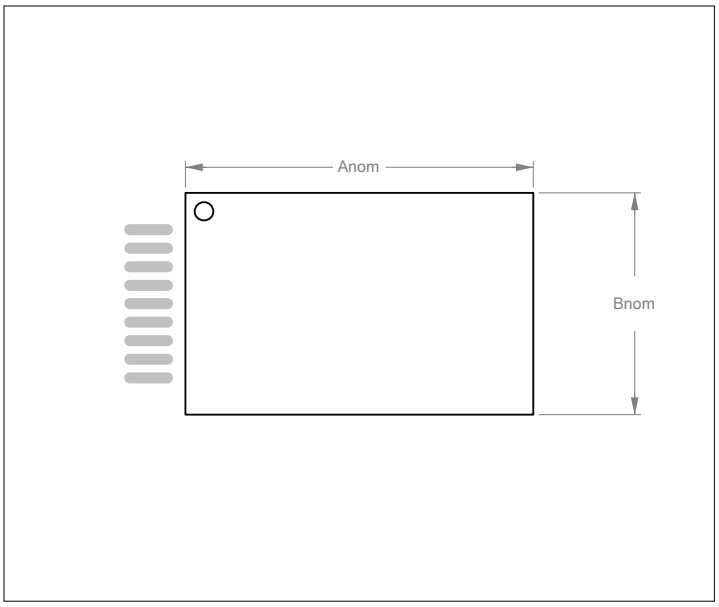



Fig.5

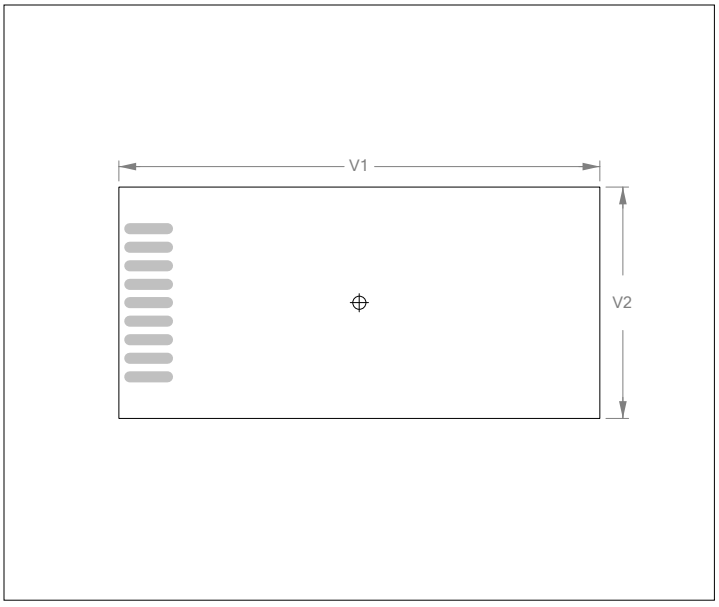



Fig.6